

FORM LAYER OF MATERIAL ON WAFER HAVING THICK AND THIN REGIONS 102

FORM NARROW AND WIDE REGIONS IN THE LAYER OF MATERIAL THAT CORRESPOND TO THICK AND THIN REGIONS OF THE WAFER 104

<u>100</u>

FIG. 1

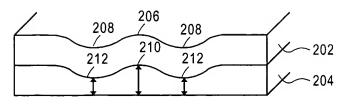


FIG. 2A

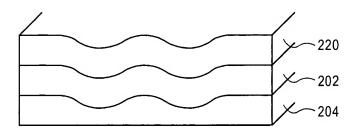


FIG. 2B

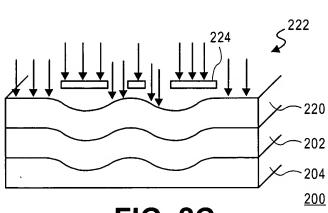


FIG. 2C

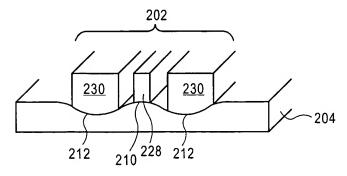
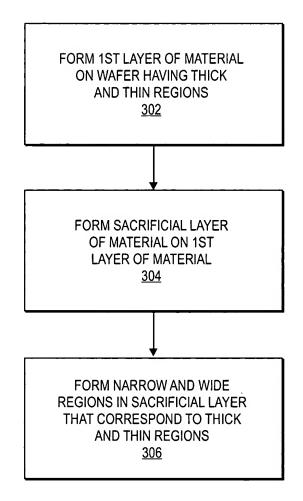


FIG. 2D



<u>300</u>

FIG. 3

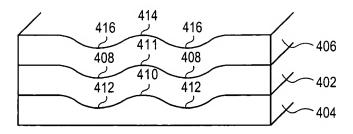


FIG. 4A

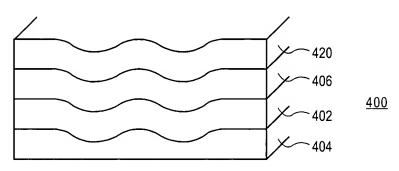


FIG. 4B

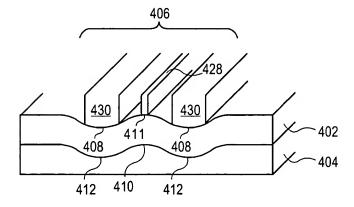


FIG. 4C

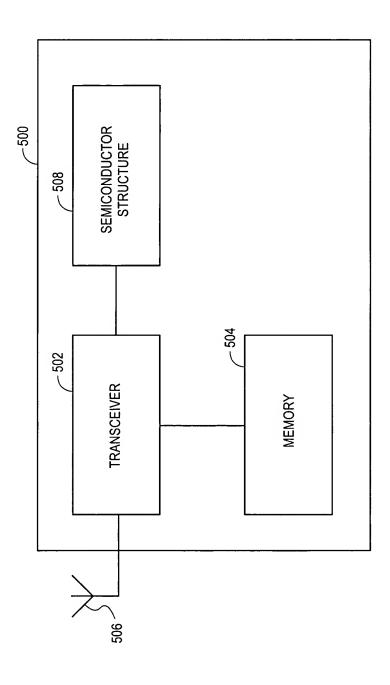


FIG. 5

400

3 I